IN THE ABSTRACT:

Please amend the Abstract as indicated below:

~~Improved injection molding machine~~ A thick-film electric heater ~~apparatus using~~ having thick-film layers applied directly on a thermally conductive non-flat substrate ~~or directly onto the melt channel~~. Preferably, the substrate is cylindrically shaped ~~with a slot running the length of the substrate~~. ~~The thick film layers and substrate have substantially equal coefficient of thermal expansion. Preferably, the heater assembly has a lower coefficient of thermal expansion than the machine channel it is installed on so as to increase the thermal communication as they heat up. A heat resistant connector housing is slidably installed over the heater assembly for mechanical connection of conductors to the heater without the use of soldering, brazing, welding or other failure prone connection means.~~ A dielectric layer is silk-screened on the substrate surface. A resistive layer is silk-screened on the dielectric layer to form a circuit for the generation of heat. The resistive layer has at least one resistive trace in a pattern that is discontinuous circumferentially. At least a pair of silk-screened contact pads are applied in electrical communication with the resistive layer for electrical connection to a power source. An insulation layer is applied over the resistive layer.